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Kind regards,

Team Nexperia

# PDTA123T series

PNP resistor-equipped transistors;  
 $R1 = 2.2 \text{ k}\Omega$ ,  $R2 = \text{open}$

Rev. 02 — 3 September 2009

Product data sheet

## 1. Product profile

### 1.1 General description

PNP Resistor-Equipped Transistors (RET) family.

Table 1. Product overview

Type number	Package			NPN complement
	NXP	JEITA	JEDEC	
PDTA123TE	SOT416	SC-75	-	PDTC123TE
PDTA123TK	SOT346	SC-59A	TO-236	PDTC123TK
PDTA123TM	SOT883	SC-101	-	PDTC123TM
PDTA123TS <sup>[1]</sup>	SOT54	SC-43A	TO-92	PDTC123TS
PDTA123TT	SOT23	-	TO-236AB	PDTC123TT
PDTA123TU	SOT323	SC-70	-	PDTC123TU

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#))

### 1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- 100 mA output current capability
- Reduces component count
- Reduces pick and place costs

### 1.3 Applications

- Digital applications
- Cost-saving alternative for BC857 series in digital applications
- Controlling IC inputs
- Switching loads

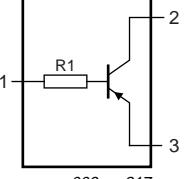
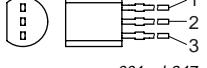
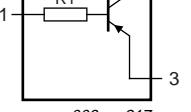
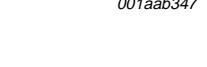
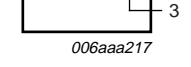
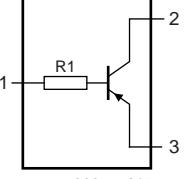
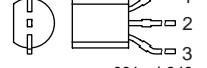
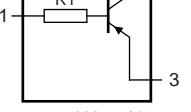
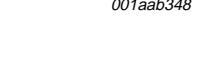
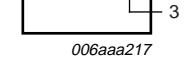
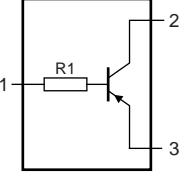
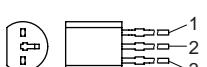
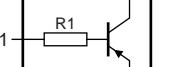
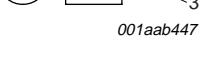
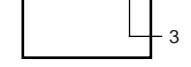
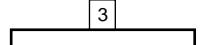
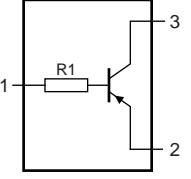
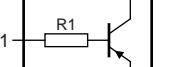
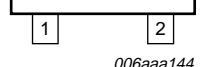
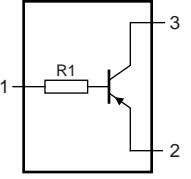
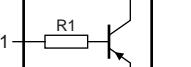
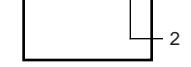
### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	-50	V
$I_o$	output current		-	-	-100	mA
R1	bias resistor 1 (input)		1.54	2.2	2.86	$\text{k}\Omega$

## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
<b>SOT54</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT54A</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT54 variant</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT23; SOT323; SOT346; SOT416</b>			
1	input (base)		
2	GND (emitter)		
3	output (collector)		
<b>SOT883</b>			
1	input (base)		
2	GND (emitter)		
3	output (collector)		

### 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTA123TE	SC-75	plastic surface mounted package; 3 leads	SOT416
PDTA123TK	SC-59A	plastic surface mounted package; 3 leads	SOT346
PDTA123TM	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883
PDTA123TS <sup>[1]</sup>	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTA123TT	-	plastic surface mounted package; 3 leads	SOT23
PDTA123TU	SC-70	plastic surface mounted package; 3 leads	SOT323

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#) and [Section 9](#))

### 4. Marking

Table 5. Marking codes

Type number	Marking code <sup>[1]</sup>
PDTA123TE	2A
PDTA123TK	GA
PDTA123TM	FA
PDTA123TS	TA123T
PDTA123TT	ZL*
PDTA123TU	*1S

[1] \* = -: made in Hong Kong

\* = p: made in Hong Kong

\* = t: made in Malaysia

\* = W: made in China

## 5. Limiting values

**Table 6. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-5	V
I <sub>O</sub>	output current		-	-100	mA
I <sub>CM</sub>	peak collector current	single pulse; $t_p \leq 1 \text{ ms}$	-	-100	mA
P <sub>tot</sub>	total power dissipation	$T_{\text{amb}} \leq 25 \text{ }^{\circ}\text{C}$			
	SOT416		[1]	-	150 mW
	SOT346		[1]	-	250 mW
	SOT883		[2][3]	-	250 mW
	SOT54		[1]	-	500 mW
	SOT23		[1]	-	250 mW
	SOT323		[1]	-	200 mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>j</sub>	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air				
	SOT416		[1]	-	-	833 K/W
	SOT346		[1]	-	-	500 K/W
	SOT883		[2][3]	-	-	500 K/W
	SOT54		[1]	-	-	250 K/W
	SOT23		[1]	-	-	500 K/W
	SOT323		[1]	-	-	625 K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

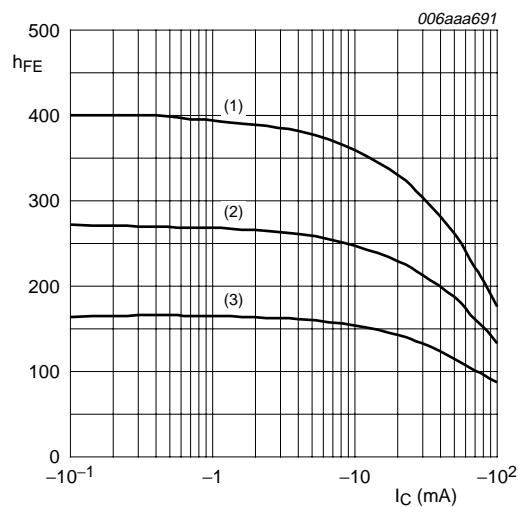
[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

## 7. Characteristics

**Table 8. Characteristics**

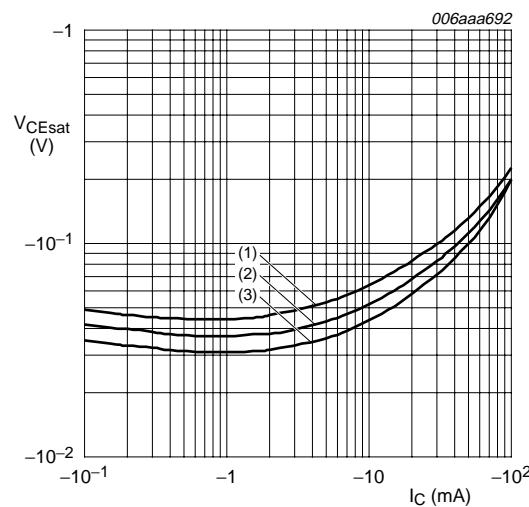
$T_{amb} = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -50\text{ V}$ ; $I_E = 0\text{ A}$	-	-	-100	nA	
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$	-	-	-1	μA	
		$V_{CE} = -30\text{ V}$ ; $I_B = 0\text{ A}$ ; $T_j = 150^\circ\text{C}$	-	-	-50	μA	
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}$ ; $I_C = 0\text{ A}$	-	-	-100	nA	
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V}$ ; $I_C = -20\text{ mA}$	30	-	-	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA}$ ; $I_B = -0.5\text{ mA}$	-	-	-150	mV	
$R_1$	bias resistor 1 (input)			1.54	2.2	2.86	kΩ
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}$ ; $I_E = i_e = 0\text{ A}$ ; $f = 1\text{ MHz}$	-	-	3	pF	



$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = 100^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = -40^\circ\text{C}$

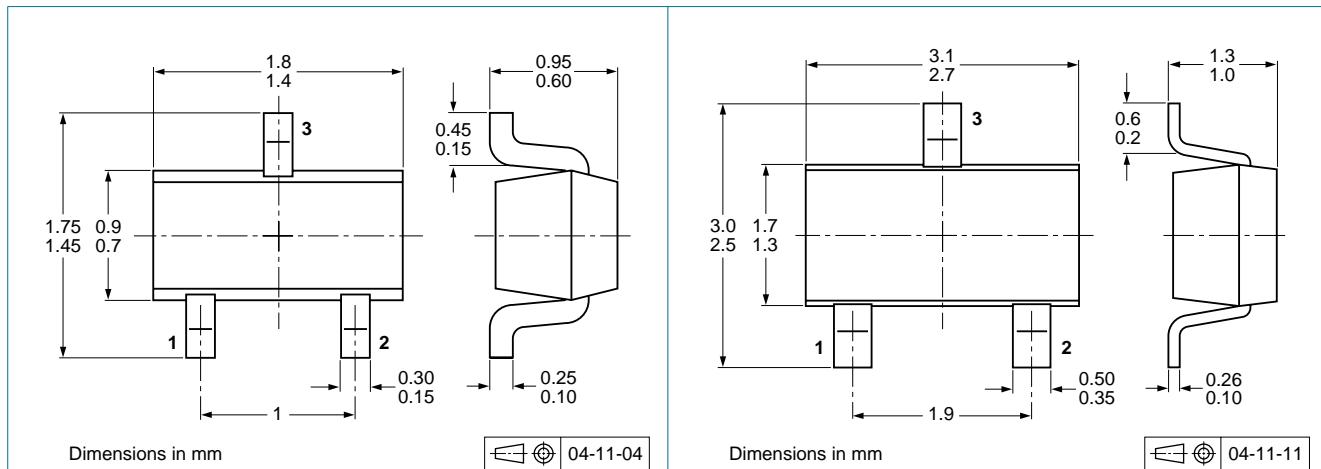
**Fig 1. DC current gain as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 100^\circ\text{C}$   
 (2)  $T_{amb} = 25^\circ\text{C}$   
 (3)  $T_{amb} = -40^\circ\text{C}$

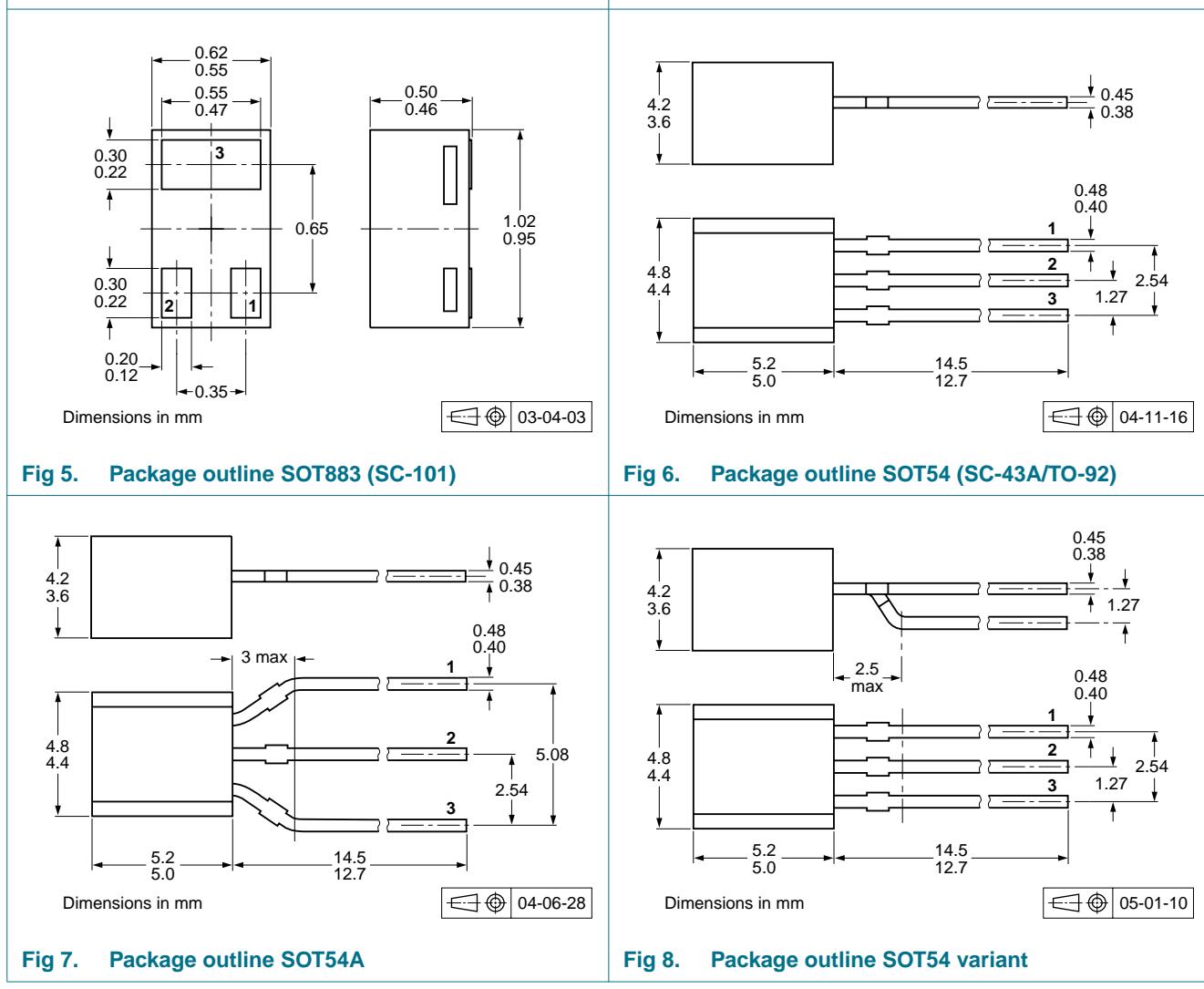
**Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values**

## 8. Package outline



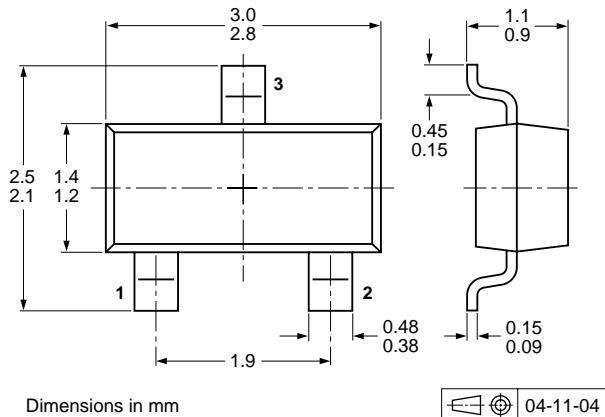
**Fig 3. Package outline SOT416 (SC-75)**

**Fig 4. Package outline SOT346 (SC-59A/TO-236)**

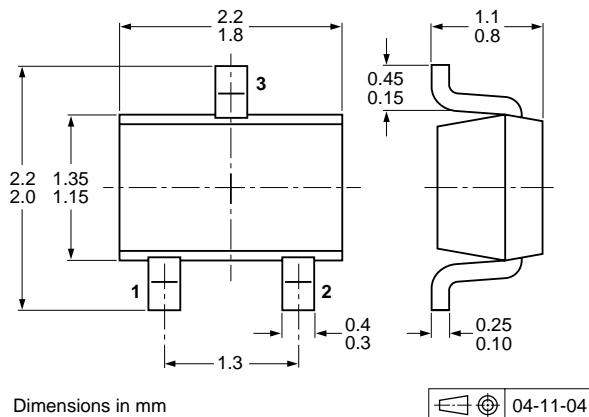


**Fig 7. Package outline SOT54A**

**Fig 8. Package outline SOT54 variant**



**Fig 9. Package outline SOT23 (TO-236AB)**



**Fig 10. Package outline SOT323 (SC-70)**

## 9. Packing information

**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.[\[1\]](#)

Type number	Package	Description	Packing quantity		
			3000	5000	10000
PDTA123TE	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTA123TK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTA123TM	SOT883	2 mm pitch, 8 mm tape and reel	-	-	-315
PDTA123TS	SOT54	bulk, straight leads	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-116
		tape ammopack, wide pitch	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-112	-
PDTA123TT	SOT23	4 mm pitch, 8 mm tape and reel	-215		-235
PDTA123TU	SOT323	4 mm pitch, 8 mm tape and reel	-115		-135

[1] For further information and the availability of packing methods, see [Section 12](#).

## 10. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTA123T_SER_2	20090903	Product data sheet	-	PDTA123T_SER_1
Modifications:	<ul style="list-style-type: none"><li>• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li></ul>			
PDTA123T_SER_1	20060307	Product data sheet	-	-

## 11. Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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